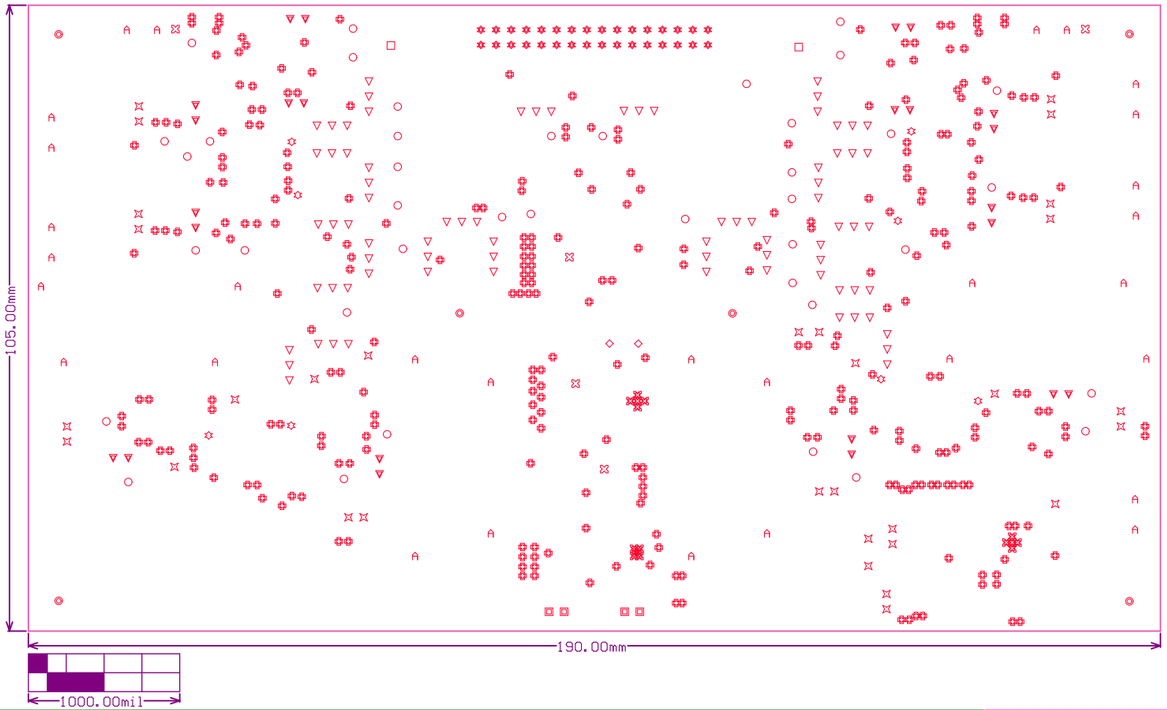
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	4.3	
3	Top Layer	Copper	1.38mil		
4	Dielectric1	FR-4 High Tg	6.70mil	4.3	
5	GND	Copper	1.38mil		
6	Dielectric 2	FR-4 High Tg	43.00mil	4.3	
7	PWR	Copper	1.38mil		
8	Dielectric 3	FR-4 High Tg	6.70mil	4.3	
9	Bottom Layer	Copper	1.38mil		
10	Bottom Solder	Solder Resist	0.40mil	4.3	
11	Bottom Overlay				



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair
✖	15	7,87mil (0,200mm)	PTH	Round	Top Layer - Bottom Layer
✪	295	12,00mil (0,305mm)	PTH	Round	Top Layer - Bottom Layer
✡	8	17,72mil (0,450mm)	PTH	Round	Top Layer - Bottom Layer
⊠	5	20,00mil (0,508mm)	PTH	Round	Top Layer - Bottom Layer
▽	78	35,04mil (0,890mm)	PTH	Round	Top Layer - Bottom Layer
▼	24	38,00mil (0,965mm)	PTH	Round	Top Layer - Bottom Layer
⌘	31	40,00mil (1,016mm)	PTH	Round	Top Layer - Bottom Layer
✲	32	40,94mil (1,040mm)	PTH	Round	Top Layer - Bottom Layer
◘	4	44,00mil (1,118mm)	PTH	Round	Top Layer - Bottom Layer
⍝	30	49,37mil (1,254mm)	PTH	Round	Top Layer - Bottom Layer
◇	2	63,00mil (1,600mm)	PTH	Round	Top Layer - Bottom Layer
○	40	80,71mil (2,050mm)	PTH	Round	Top Layer - Bottom Layer
□	2	125,00mil (3,175mm)	PTH	Round	Top Layer - Bottom Layer
◎	6	125,98mil (3,200mm)	PTH	Round	Top Layer - Bottom Layer
	572 Total				

FOR 7.87MIL DRILL +0/-7.87MIL
FOR 12MIL DRILL +0/-12MIL
FOR PTH DRILL +/-3MIL

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 7.874 MIL
MIN. VIA PAD SIZE: 19.685 MIL
MINIMUM ANNULAR RING 0.15mm (5.906MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [X] NO [ ]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [ ] NO [X]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

TEXAS INSTRUMENTS

PROJECT TITLE: TIDA-00834E2
DESIGNED FOR: Public Release
FILE NAME: TIDA-00834E2_PCB.PcbDoc

ENGINEER: Sreenivasa	LAYOUT BY: Manjunath M
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00834	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00834		
PLOT NAME = Fabrication Drawing	GENERATED : 11/25/2016 5:07:14 PM		TEXAS INSTRUMENTS

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